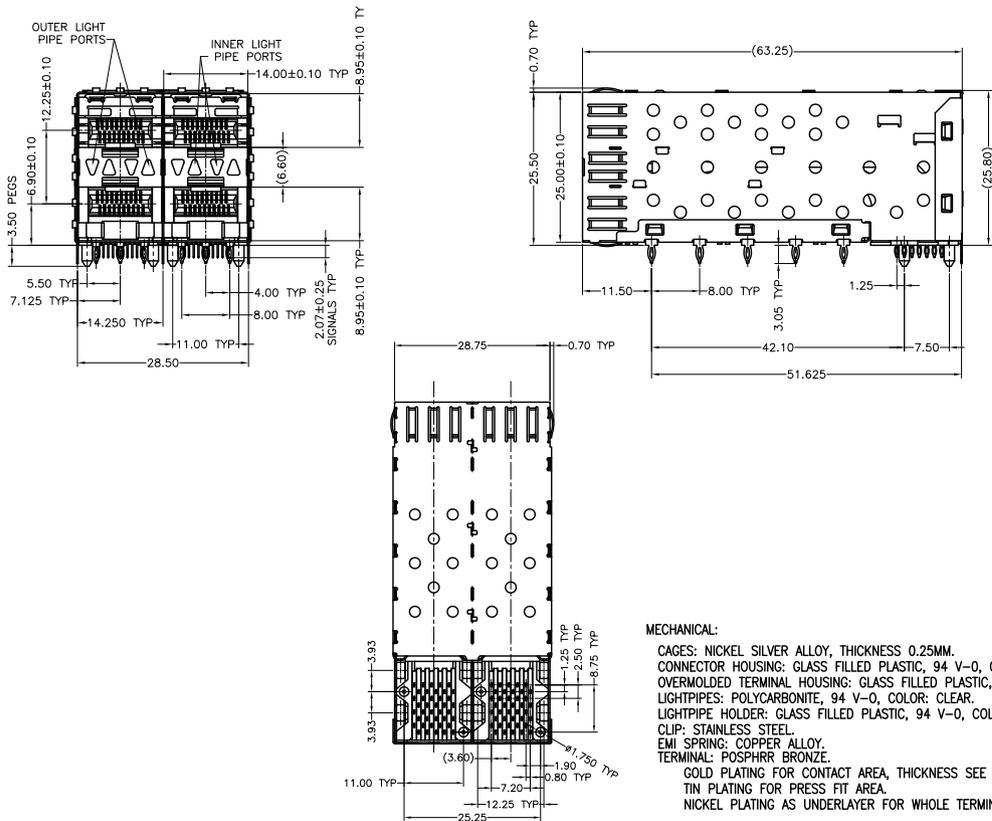


SFP*XFP*QSFP/QSFP+ Connectors

KLS12-SFP-019

Electrical Specifications:

VOLTAGE: 30 VOLTS AC.
CURRENT: 0.50 A PER CONTACT.
CONTACT RESISTANCE:50 MILLIOHMS MAX;
INSULATION RESISTANCE:1000 MEGAOHMS MIN
AT 100 VDC FOR 1 MINUTE.
DIELECTRIC WITHSTANDING VOLTAGE:300 VDC MIN;
TEMPERATURE:
OPERATION: -40°C~+85°C
STORAGE: -55°C~+105°C
LIGHTPIPE PAD LAYOUT IS FOR LOW-PROFILE LED PACKAGE.
LED SIZE(LxWxH): 2x1x0.4MM MAX.
RoHS COMPLIANCE.



MECHANICAL:

CAGES: NICKEL SILVER ALLOY, THICKNESS 0.25MM.
CONNECTOR HOUSING: GLASS FILLED PLASTIC, 94 V-0, COLOR: BLACK.
OVERMOLDED TERMINAL HOUSING: GLASS FILLED PLASTIC, 94 V-0, COLOR: BLACK.
LIGHTPIPES: POLYCARBONITE, 94 V-0, COLOR: CLEAR.
LIGHTPIPE HOLDER: GLASS FILLED PLASTIC, 94 V-0, COLOR: BLACK.
CLIP: STAINLESS STEEL.
EMI SPRING: COPPER ALLOY.
TERMINAL: POSPHRR BRONZE.
GOLD PLATING FOR CONTACT AREA, THICKNESS SEE OPTION.
TIN PLATING FOR PRESS FIT AREA.
NICKEL PLATING AS UNDERLAYER FOR WHOLE TERMINAL.

ORDER INFORMATION

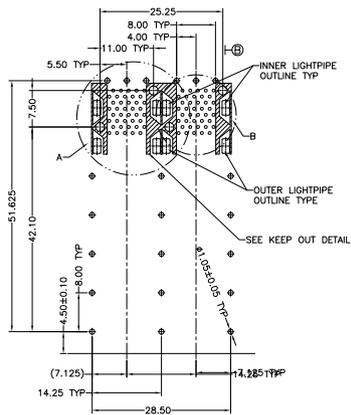
KLS12-SFP-019

Part Number

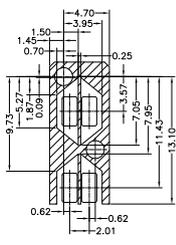
SFP*XFP*QSFP/QSFP+ Connectors

KLS12-SFP-019

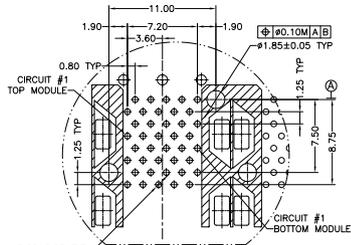
XII



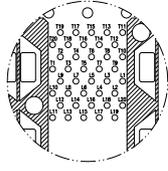
RECOMMENDED PCB LAYOUT—COMPONENT SIDE
PCB THICKNESS 1.6MM MIN
TOLERANCE: ±0.05 MM



KEEP OUT ZONE DETAIL
SCALE: 2:1

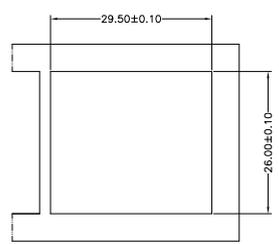


DETAIL A
SCALE: 2:1

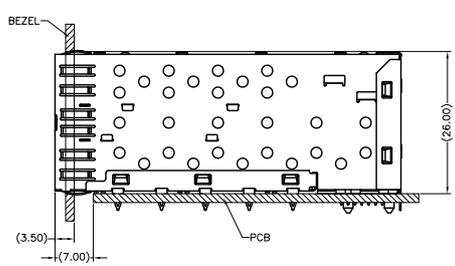


CONNECTOR PIN—OUT DETAIL
COMPONENT SIDE OF BOARD
DETAIL B
SCALE: 2:1

NOTE FOR ϕ :
THE CURVED TAILS THAT GO INTO THE HOLES LOCATED BY THESE DIMENSIONS ARE BEING ELIMINATED.
TO ACCOMMODATE THIS CONVERSION, IT IS RECOMMENDED THAT BOARDS DESIGNED TO THIS PRINT
REVISION INCLUDE THESE HOLES.



RECOMMENDED BEZEL CUT—OUT CENTER DETAIL
BEZEL THICKNESS 0.8~2.6MM



ORDER INFORMATION

KLS12-SFP-019

Part Number